

IN THE ABSTRACT OF THE DISCLOSURE:

~~This invention is a~~ A paste composition ~~containing~~ contains an inorganic filler, a resin and a solvent, wherein the paste composition is characterized in that it contains one or more solvents of which the boiling point is 160°C or higher and an inorganic filler of which the mean particle diameter is 5 µm or smaller, and the total content of the solvent ~~being~~ is 25 wt% or less based on the total amount of the paste composition, and ~~relates to~~ a dielectric composition ~~containing~~ contains an inorganic filler and resin, wherein the inorganic filler includes inorganic fillers of at least two kinds of mean particle diameter, and the greatest mean particle diameter of said mean particle diameters is 0.1-5 µm and is 3 times or more to the minimum mean particle diameter.

~~By this invention, it~~ It is possible to obtain a high dielectric constant composition of which linear expansion coefficient is low, and which has a large capacitance.